

What is claimed is:

1. A method of manufacturing an electronic device, the method comprising:
forming an external terminal on an interconnect pattern formed on a substrate;

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subsequently mounting a chip component having an electrode on the substrate,
and forming an interconnect for electrically connecting the electrode and the
interconnect pattern at a temperature lower than a melting point of the external terminal.

10 2. The method of manufacturing an electronic device as defined by claim 1,
wherein the interconnect is formed of a dispersant including electrically
conductive particles.

15 3. The method of manufacturing an electronic device as defined by claim 2, further
comprising:

forming an insulating section adjacent to the chip component,
wherein the step of forming the interconnect includes ejecting a dispersant
including the electrically conductive particles over the insulating section and the
interconnect pattern.

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4. The method of manufacturing an electronic device as defined by claim 3,
wherein the insulating section is formed of a resin.

25 5. The method of manufacturing an electronic device as defined by claim 3,
wherein the insulating section is formed to have an inclined surface descending
in an outward direction from the chip component.

6. The method of manufacturing an electronic device as defined by claim 4,
wherein the insulating section is formed to have an inclined surface descending
in an outward direction from the chip component.
- 5 7. The method of manufacturing an electronic device as defined by claim 1,
wherein the chip component is a semiconductor element.
8. An electronic device manufactured by the method as defined by claim 1.
- 10 9. A circuit board on which the electronic device as defined by claim 8 is mounted.
10. An electronic instrument having the electronic device as defined by claim 8.
11. A chip carrier comprising:
15 an external terminal formed of a soldering material, the external terminal being
provided on an interconnect pattern formed on a substrate; and
a region connected to an electrode which is included in a chip component.